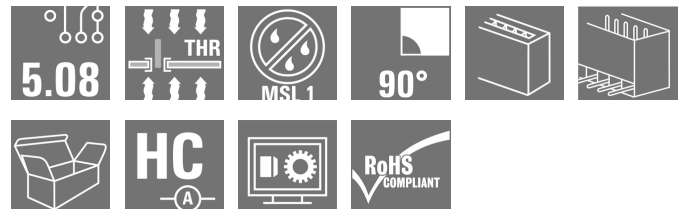


**OMNIMATE Signal - series BL/SL 5.08
SL-SMT 5.08HC/02/90G 3.2SN BK BX**

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



High-temperature-resistant pin header, packed in box or tape. On tape, with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Type	SL-SMT 5.08HC/02/90G 3.2SN BK BX
Order No.	1780180000
Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 5.08 mm, No. of poles: 2, 90°, Solder pin length (l): 3.2 mm, tinned, Black, Box
GTIN (EAN)	4032248165506
Qty.	100 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Box

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Technical data**Dimensions and weights**

Height of lowest version	8.4 mm	Depth	12 mm
Depth (inches)	0.472 inch	Net weight	1.43 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Mounting onto the PCB	THT/THR solder connection
Pitch in mm (P)	5.08 mm	Pitch in inches (P)	0.2 inch
Outgoing elbow	90°	No. of poles	2
Number of solder pins per pole	1	Solder pin length (l)	3.2 mm
Solder pin length tolerance	0 / -0.3 mm	Tolerance of solder pin position	± 0.1 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.4 mm
Solder eyelet hole diameter tolerance (D)	+ 0,1 mm	L1 in mm	5.08 mm
L1 in inches	0.2 inch	Number of rows	1
Pin series quantity	1	Can be coded	Yes
Plugging cycles	25		

Material data

Insulating material	LCP GF	Colour	Black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
CTI	≥ 175	Insulation resistance	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact material	CuMg	Contact surface	tinned
Layer structure of solder connection	1-3 μm Ni / 2-4 μm Sn matt	Layer structure of plug contact	1-3 μm Ni / 2-4 μm Sn matt
Storage temperature, min.	-25 °C	Storage temperature, max.	55 °C
Max. relative humidity during storage	80 %	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC


tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. no. of poles (Tu=20°C)	27.5 A
Rated current, max. no. of poles (Tu=20°C)	19 A	Rated current, min. no. of poles (Tu=40°C)	24 A
Rated current, max. no. of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

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Technical data

Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	200039-1176845
Rated voltage (Use group B)	300 V	Rated voltage (use group D)	300 V
Rated current (use group B)	18.5 A	Rated current (use group D)	18.5 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Rated data acc. to UL 1059

Institute (UR)		Certificate No. (UR)	E60693
Rated voltage (use group B)	300 V	Rated voltage (use group D)	300 V
Rated current (use group B)	18.5 A	Rated current (use group D)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Classifications

ETIM 3.0	EC001284	ETIM 4.0	EC002637
ETIM 5.0	EC002637	ETIM 6.0	EC002637
UNSPSC	30-21-18-10	eClass 5.1	27-26-07-04
eClass 6.2	27-26-07-04	eClass 7.1	27-44-04-02
eClass 8.1	27-44-04-02	eClass 9.0	27-44-04-02
eClass 9.1	27-44-04-02		

Notes

Notes	<ul style="list-style-type: none"> • Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Data sheet

**OMNIMATE Signal - series BL/SL 5.08
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Technical data

Approvals

Approvals



ROHS

Conform

Downloads

Approval/Certificate/Document of
Conformity

[Declaration of the Manufacturer](#)

Brochure/Catalogue

- [FL DRIVES EN](#)
- [MB SMT EN](#)
- [FL DRIVES DE](#)
- [MB DEVICE MANUF. EN](#)
- [CAT 2 PORTFOLIOGUIDE EN](#)
- [FL BUILDING SAFETY EN](#)
- [FL APPL LED LIGHTING EN](#)
- [FLIndustr.CONTROLS EN](#)
- [FL MACHINE SAFETY EN](#)
- [FL HEATING ELECTR EN](#)
- [FL APPL_INVERTER EN](#)
- [FL_BASE_STATION_EN](#)
- [FL ELEVATOR EN](#)
- [FL POWER SUPPLY EN](#)
- [FL 72H SAMPLE SER EN](#)
- [PO OMNIMATE EN](#)

Engineering Data

[EPLAN, WSCAD, Zuken E3.S](#)

Engineering Data

[STEP](#)

SMT white paper

[Download Whitepaper](#)

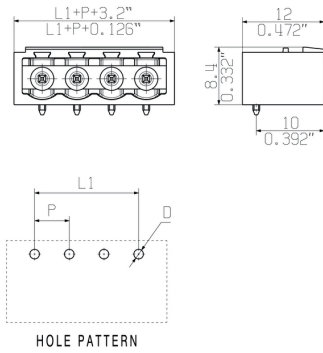
Data sheet

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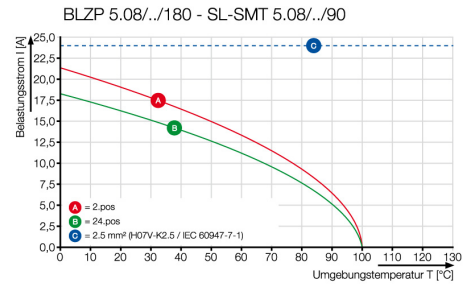
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Drawings

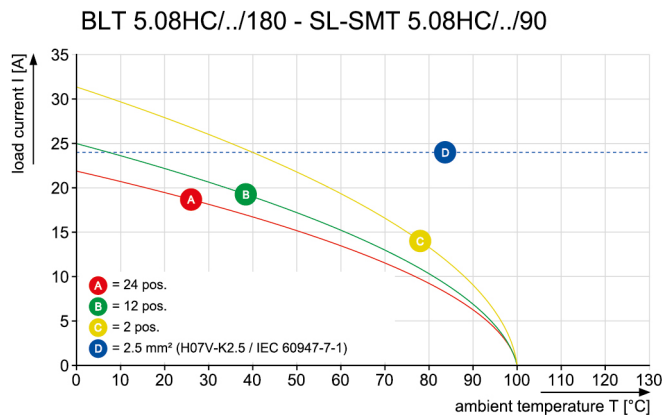
Dimensional drawing



Graph



Graph



Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

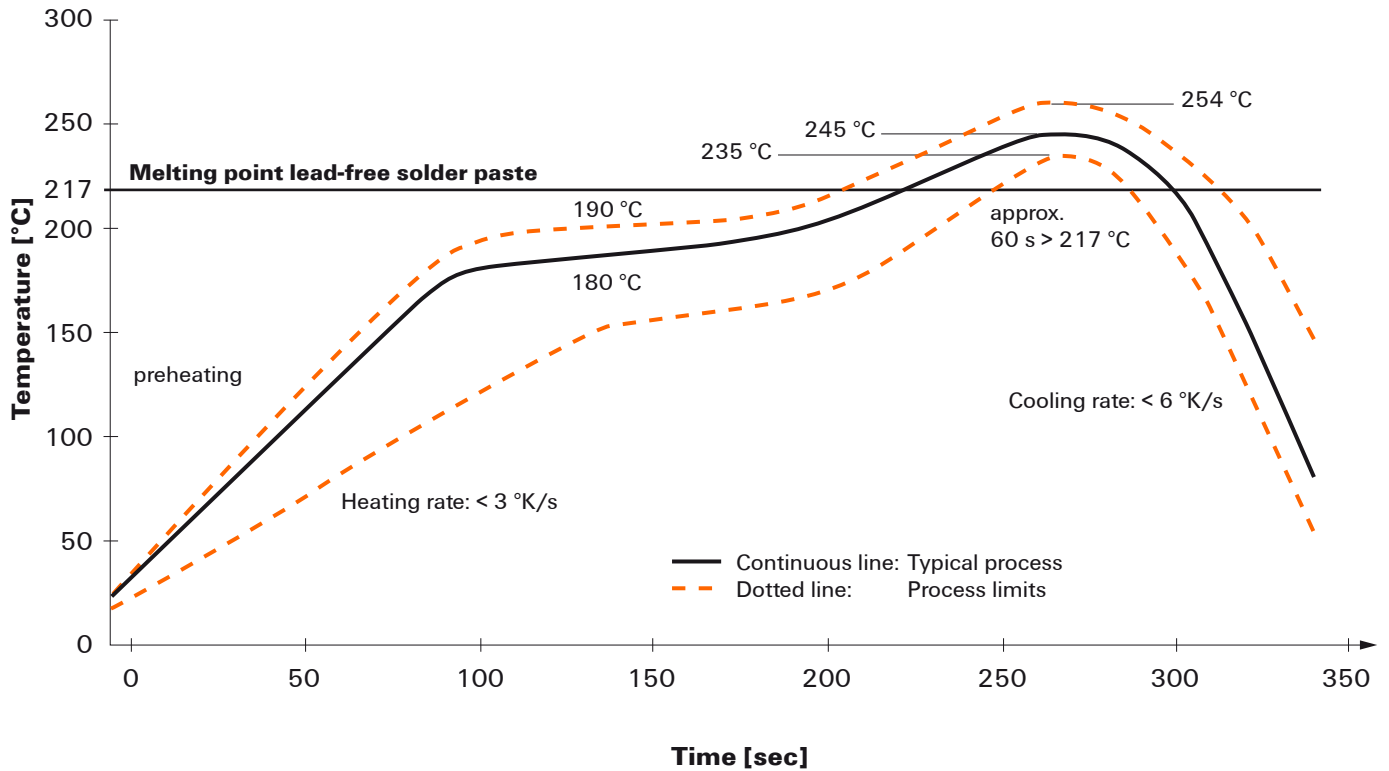
When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is ‚activated‘. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.